

Features:

- Fast Switching
- Low Gate Charge and $R_{DS(ON)}$
- Low Reverse transfer capacitances

Applications:

- DC-DC converter
- Portable Equipment
- Power management

General Description:

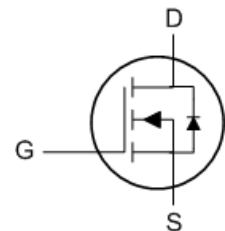
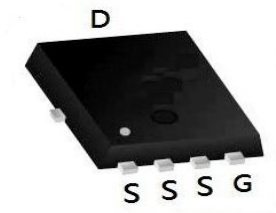
The XRS75N10F uses super trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications. The package form is PDFN5060-8L, which accords with the ROHS standard and Halogen Free standard.

100% DVDS Tested

100% Avalanche Tested

Product Summary

BVDSS	RDSON	ID
100V	6.2mΩ	75A

PDFN5060-8L Pin Configuration**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	75	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	51	A
I_{DM}	Pulsed Drain Current ²	320	A
EAS	Single Pulse Avalanche Energy ³	150	mJ
I_{AS}	Avalanche Current	---	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation ⁴	108	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	---	1.15	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	60	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1mA$	---	---	---	$V/^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=20A$	---	6.2	7.75	$m\Omega$
		$V_{GS}=4.5V, I_D=10A$	---	7.6	8.36	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.3	1.8	2.3	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	$mV/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=100V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{DS}=100V, V_{GS}=0V, T_J=100^\circ\text{C}$	---	---	---	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=15A$	---	---	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	0.65	---	Ω
Q_g	Total Gate Charge	$V_{DS}=50V, V_{GS}=10V, I_D=20A$	---	32.1	---	nC
Q_{gs}	Gate-Source Charge		---	9.7	---	
Q_{gd}	Gate-Drain Charge		---	8.6	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=50V, I_D=20A, R_G=4\Omega, V_{GS}=10V$	---	15	---	ns
T_r	Rise Time		---	23	---	
$T_{d(off)}$	Turn-Off Delay Time		---	45	---	
T_f	Fall Time		---	35	---	
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	---	1916	---	pF
C_{oss}	Output Capacitance		---	602	---	
C_{rss}	Reverse Transfer Capacitance		---	17	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	75	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=20A, T_J=25^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=20A, di/dt=100A$	---	60	---	nS
Q_{rr}	Reverse Recovery Charge	$I_F=20A, T_J=25^\circ\text{C}$	---	110	---	nC

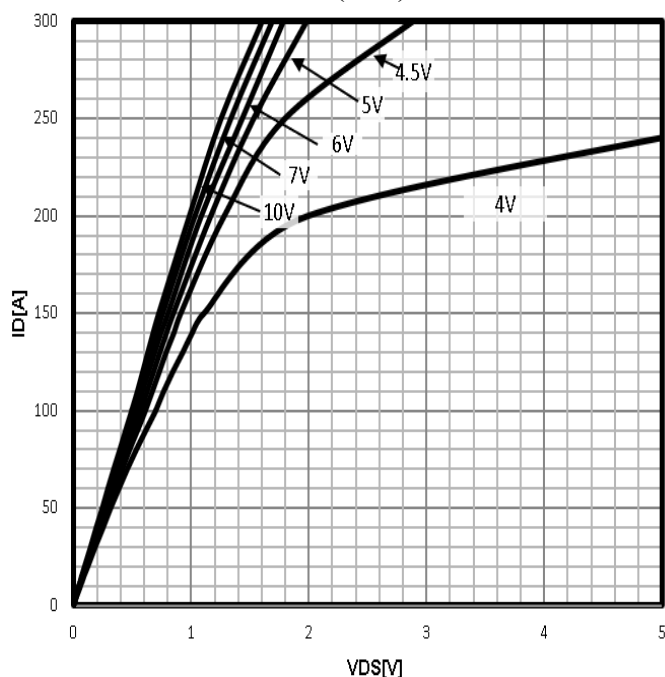
^{a1}: Repetitive rating; pulse width limited by maximum junction temperature

^{a2}: $V_{DD}=50V, L=0.3mH, R_g=25\Omega$, Starting $T_J=25^\circ\text{C}$

Characteristics Curve:

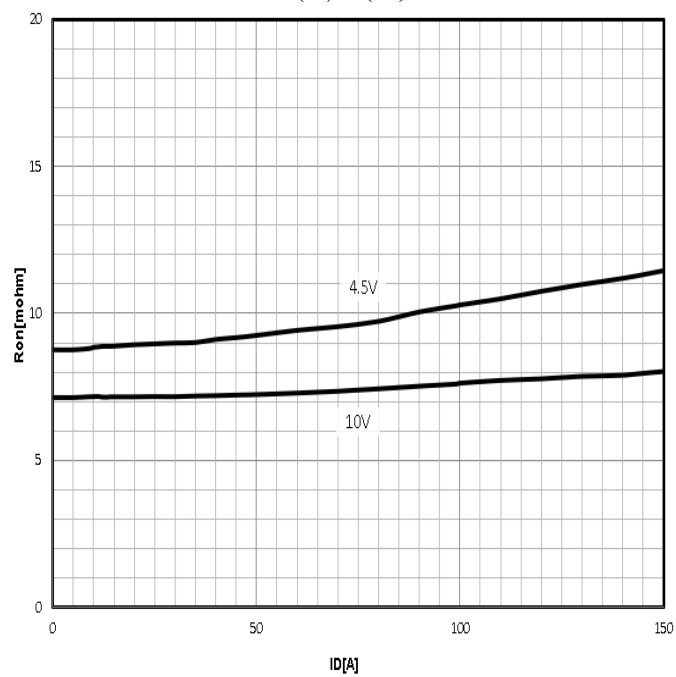
Typ. output characteristics

$$I_D = f(V_{DS})$$



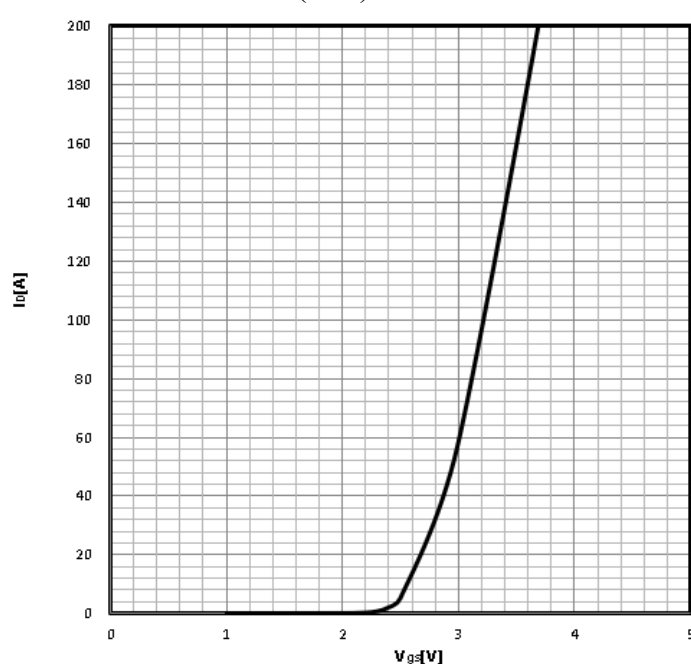
Typ. drain-source on resistance

$$R_{DS(on)} = f(I_D)$$



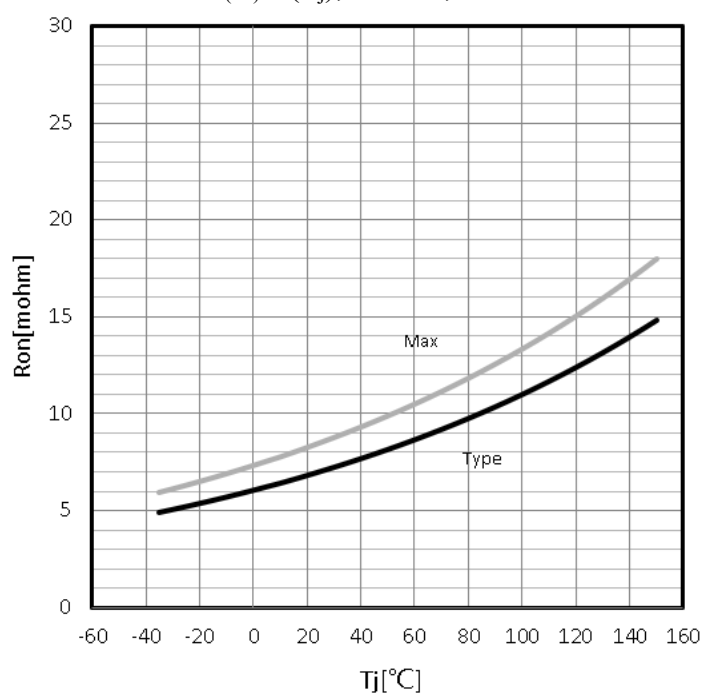
Typ. transfer characteristics

$$I_D = f(V_{GS})$$



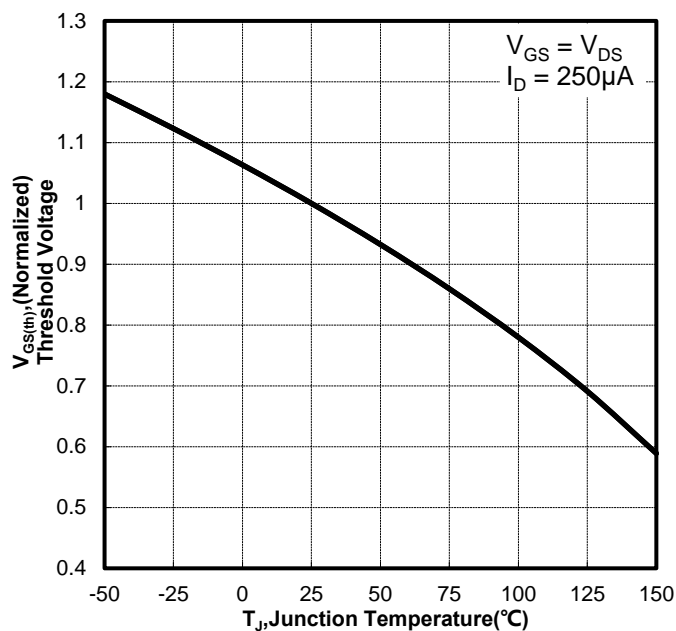
Drain-source on-state resistance

$$R_{DS(on)} = f(T_j); I_D = 20A; V_{GS} = 10V$$



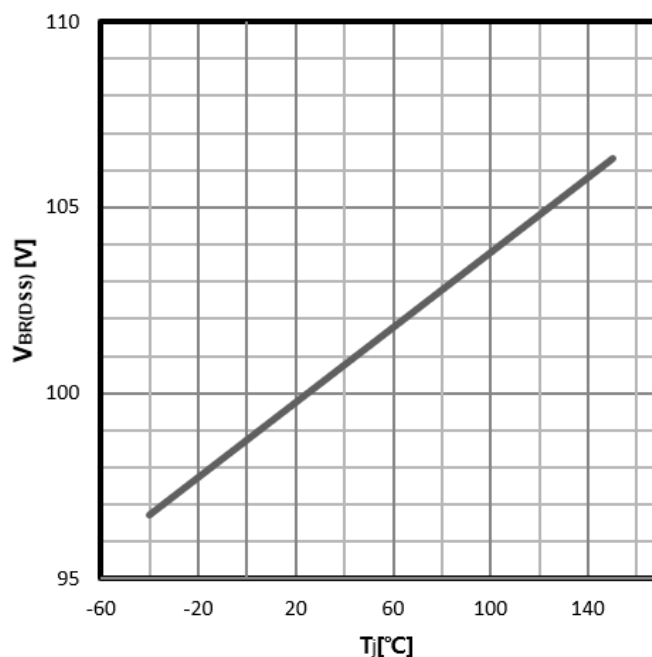
Gate Threshold Voltage

$$V_{TH}=f(T_j); I_D=250\mu A$$



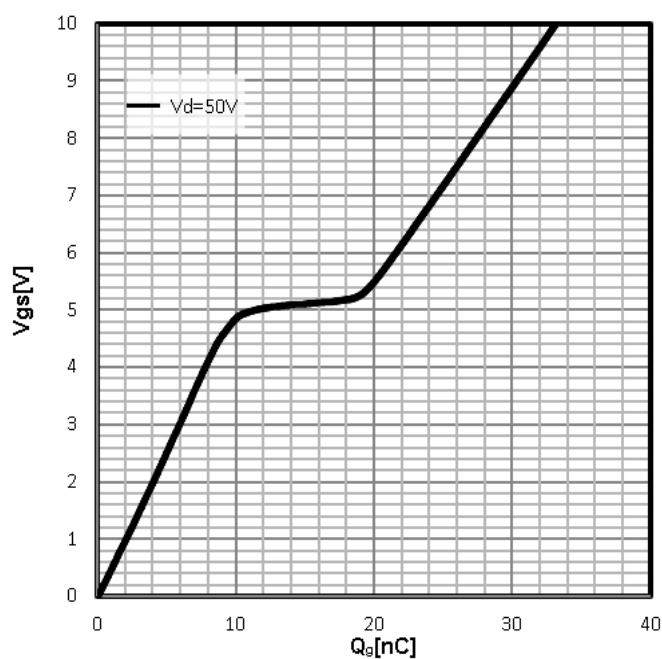
Drain-source breakdown voltage

$$V_{BR(DSS)}=f(T_j); I_D=250\mu A$$



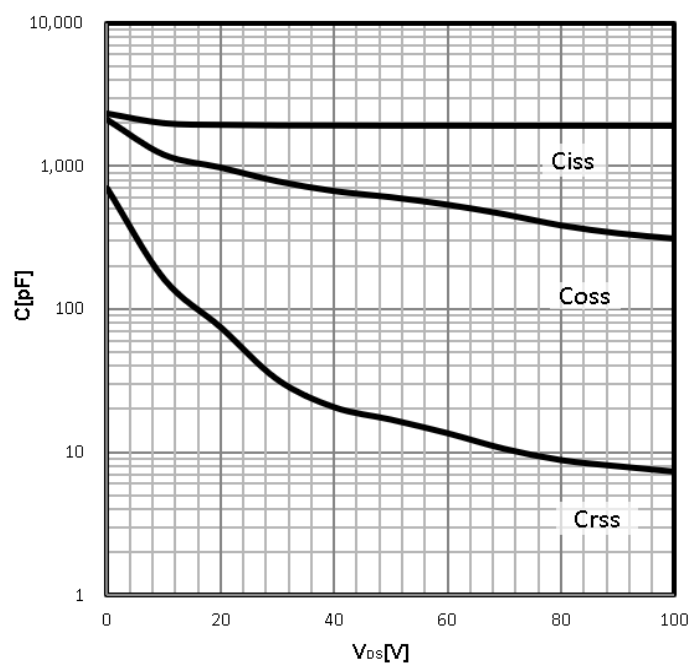
Typ. gate charge

$$V_{GS}=f(Q_g); I_D=20A$$



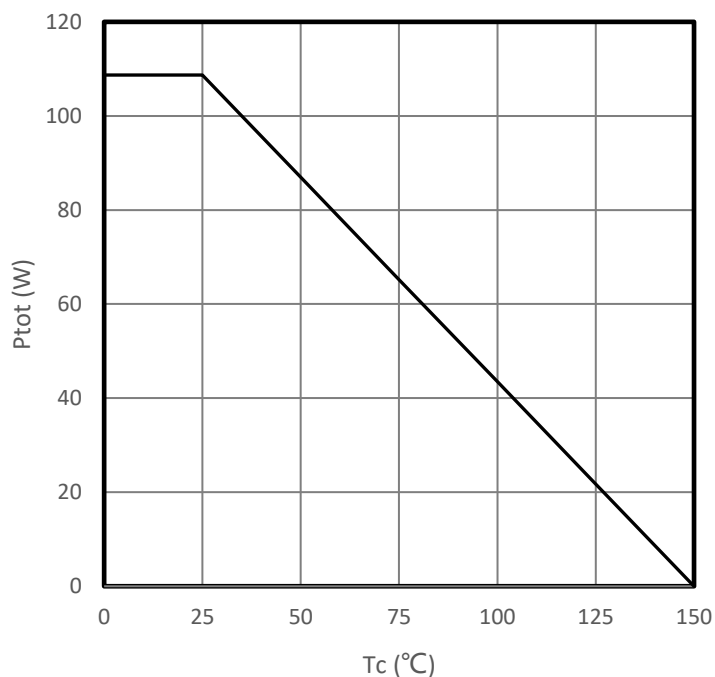
Typ. capacitances

$$C=f(V_{DS}); V_{GS}=0V; f=1MHz$$



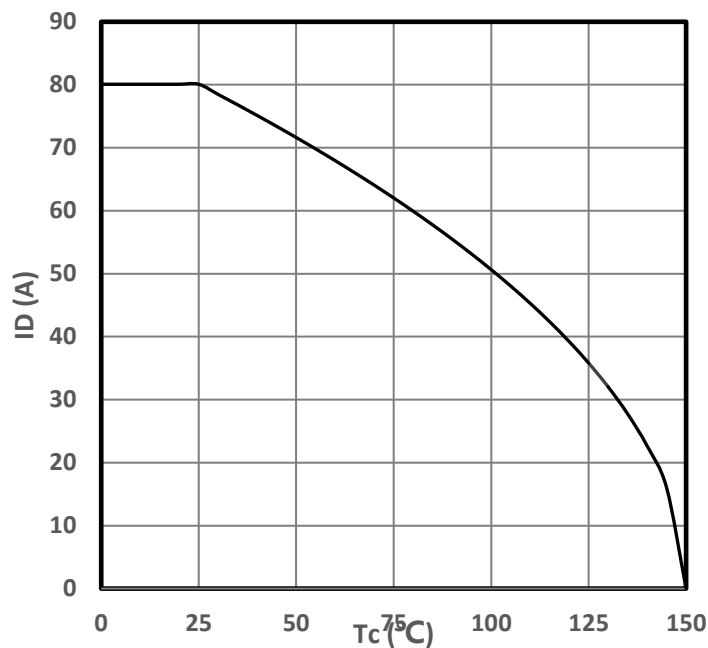
Power Dissipation

$$P_{tot}=f(T_C)$$



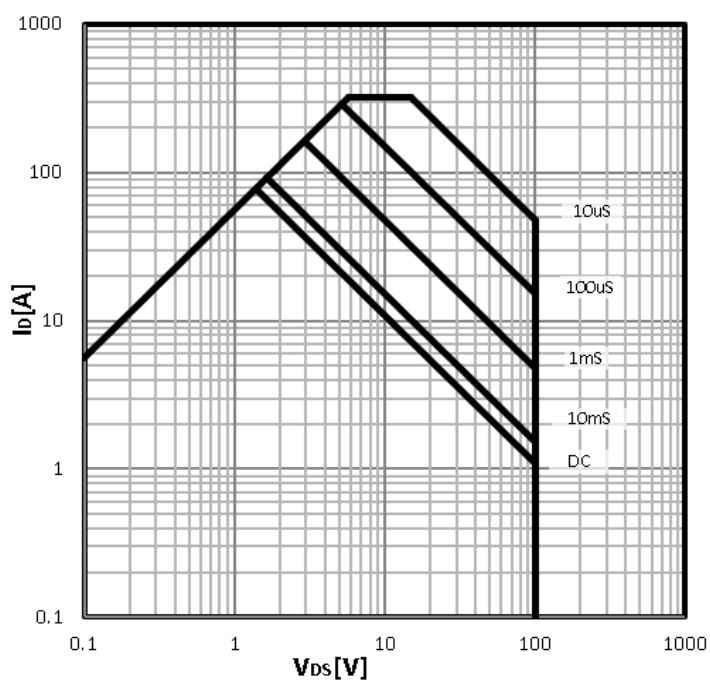
Maximum Drain Current

$$I_D=f(T_C)$$



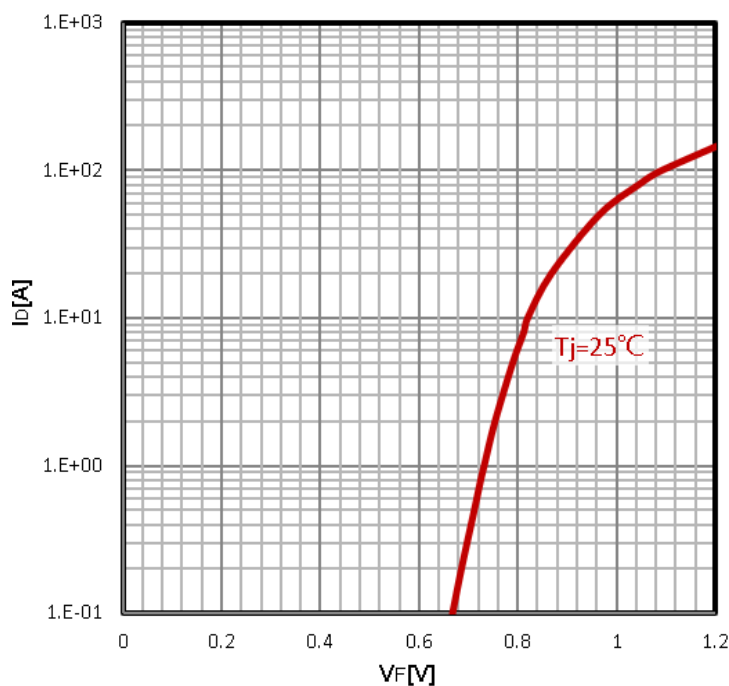
Safe operating area

$$I_D=f(V_{DS})$$



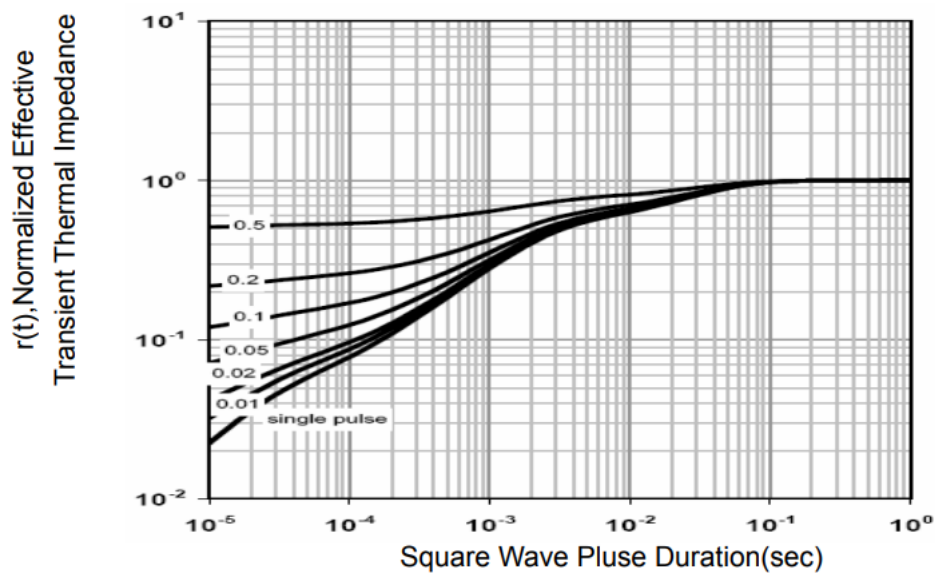
Body Diode Forward Voltage Variation

$$I_F=f(V_{GS})$$

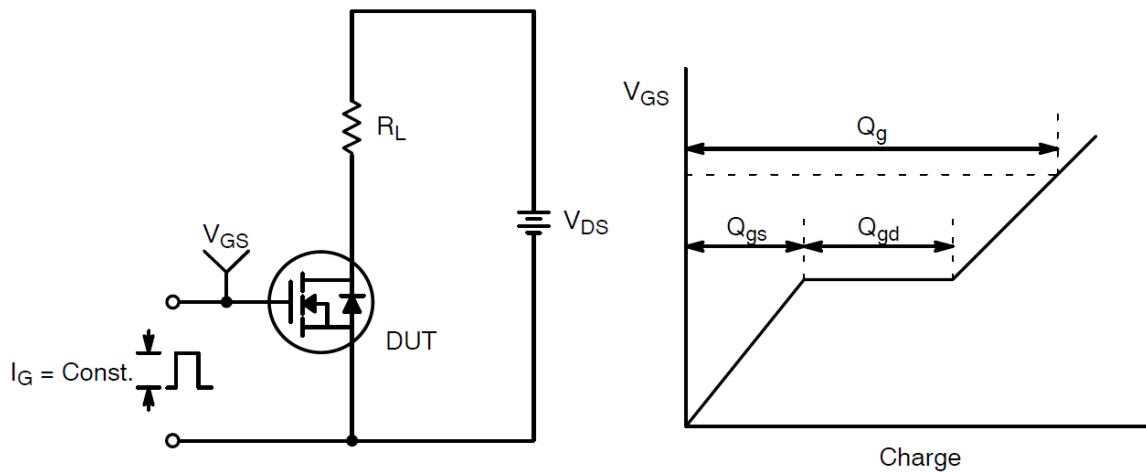


Max. transient thermal impedance

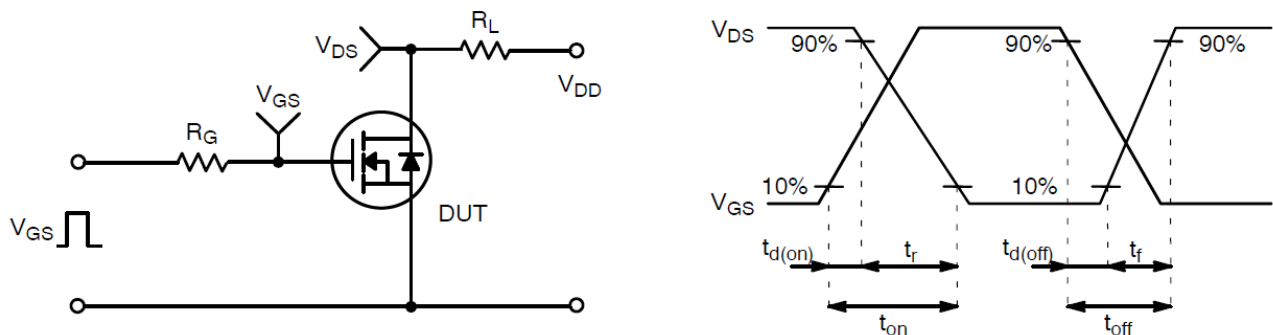
$$Z_{thJC}=f(t_p)$$



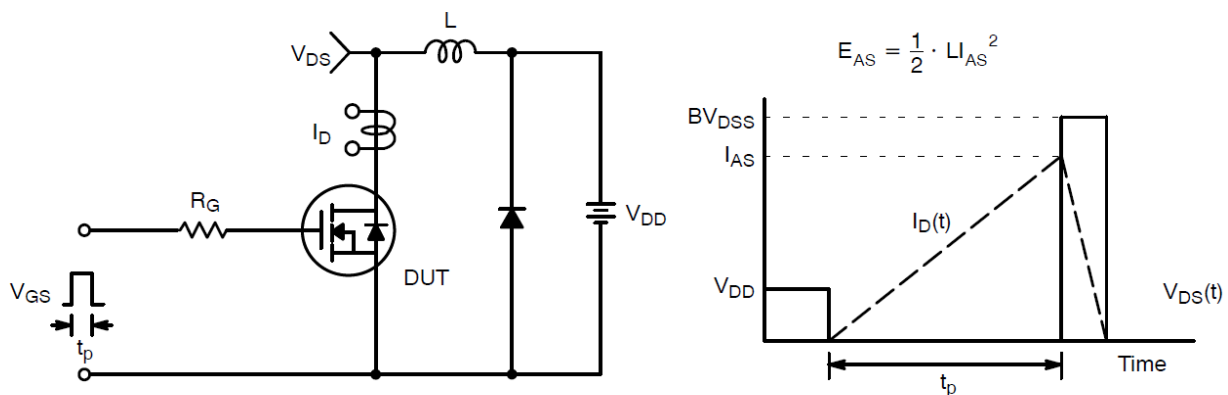
Test Circuit and Waveform:



Gate Charge Test Circuit & Waveform

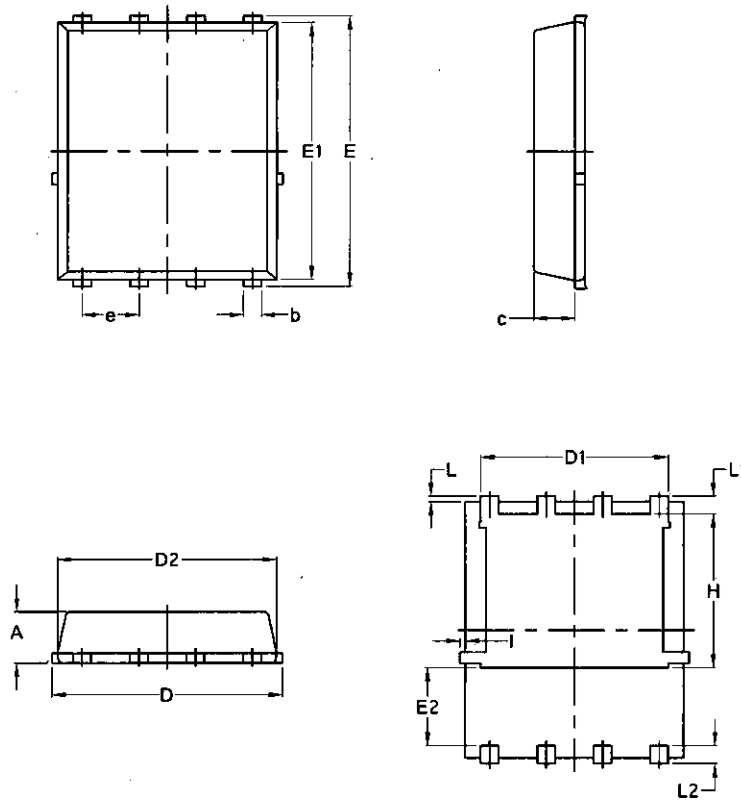


Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070